ABSTRACT OF THE DISCLOSURE

TITLE OF INVENTION: **SEMICONDUCTOR ELEMENT-MOUNTING BOARD, MANUFACTURING METHOD FORR THE BOARD, SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD FORR THE DEVICE**

Conductive members (103) formed of metallic wires constructed so that they extend linearly between a semiconductor element-mounting face (104) and a circuit board-mounting face (105) of a base member (102) are integrally molded with the base member. For this purpose, a resin material for forming the base member is injected into a mold wherein the conductive members are linearly arranged beforehand.

Figure 1.